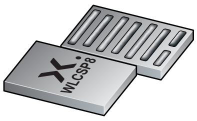


GAN3R2-100CBE

100 V, 3.2 mOhm Gallium Nitride (GaN) FET in a 3.5 mm x 2.13 mm Wafer Level Chip-Scale Package (WLCSP)

27 April 2023 Product data sheet

1. General description

The GAN3R2-100CBE is a a general purpose 100 V, 3.2 mΩ Gallium Nitride (GaN) FET in a 15 bump Wafer Level Chip-Scale Package (WLCSP). It is a normally-off e-mode device offering superior performance.

2. Features and benefits

- Enhancement mode - normally-off power switch
- Ultra high frequency switching capability
- No body diode
- Low gate charge, low output charge
- Qualified for standard applications
- ESD protection
- RoHS, Pb-free, REACH-compliant
- High efficiency and high power density
- Wafer Level Chip-Scale Package (WLCSP) 3.5 mm x 2.13 mm

3. Applications

- High power density and high efficiency power conversion
- AC-to-DC converters, (secondary stage)
- High frequency DC-to-DC converters in 48 V systems
- Fast battery charging, mobile phone, laptop, tablet and USB type-C chargers
- Datacom and telecom (AC-to-DC and DC-to-DC) converters
- Motor drives
- LiDAR (non-automotive)
- Class D audio amplifiers

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage			-	-	100	V
V_{TDS}	transient drain to source voltage	pulsed; t_p = 1 µs; δ_{factor} = 0.01		-	-	130	V
I_D	drain current	V_{GS} = 5 V	[1]	-	-	60	A
P_{tot}	total power dissipation	Fig. 1		-	-	394	W
T_j	junction temperature			-40	-	150	°C
Static characteristics							
R_{DSon}	drain-source on-state resistance	V_{GS} = 5 V; I_D = 25 A; T_j = 25 °C; Fig. 9; Fig. 10; Fig. 11; Fig. 12		-	2.4	3.2	mΩ
R_G	gate resistance	f = 5 MHz; T_j = 25 °C		-	2.2	-	Ω

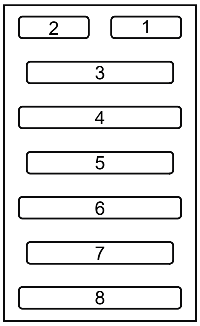
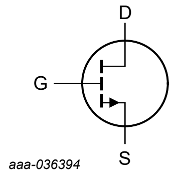
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Dynamic characteristics							
Q_{GD}	gate-drain charge	I_D = 25 A; V_{DS} = 50 V; V_{GS} = 5 V; T_j = 25 °C; Fig. 13; Fig. 14		-	1.7	-	nC
$Q_{G(tot)}$	total gate charge			-	9.2	12	nC
Q_{oss}	output charge	V_{GS} = 0 V; V_{DS} = 50 V; T_j = 25 °C	[2]	-	50	-	nC

[1] Limited by package

[2] Q_r is not specified separately from Q_{oss} for e-mode GaN FETs, since $Q_r = Q_{oss} + Q_D$, and Q_D = 0. (Q_D is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q_{oss} have to be transferred for e-mode GaN FETs.)

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 Transparent top view **WLCSP8 (WLCSP8-SOT8072)**	
2	S	source		
3	D	drain		
4	S	source		
5	D	drain		
6	S	source		
7	D	drain		
8	S	source		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
GAN3R2-100CBE	WLCSP8	wafer level chip-scale package; 8 solder bars; body: 3.5 x 2.13 x 0.429 mm	WLCSP8-SOT8072

7. Marking

Table 4. Marking codes

Type number	Marking code
GAN3R2-100CBE	3R2DCBE

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).Tj = 25 °C unless otherwise stated.

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage			-	100	V

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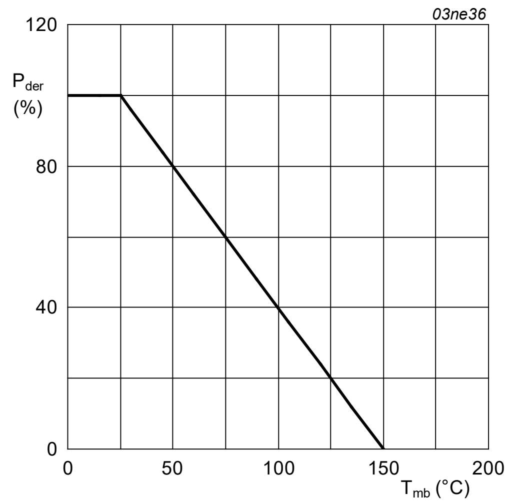
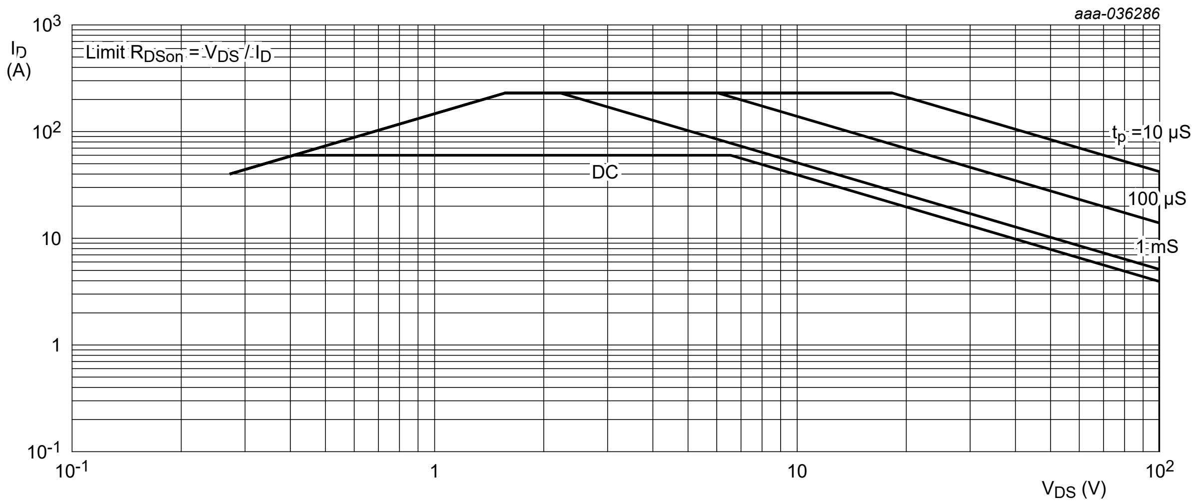
Symbol	Parameter	Conditions		Min	Max	Unit
V_{TDS}	transient drain to source voltage	pulsed; t_p = 1 µs; δ_{factor} = 0.01		-	130	V
V_{GS}	gate-source voltage			-4	6	V
P_{tot}	total power dissipation	Fig. 1		-	394	W
I_D	drain current	V_{GS} = 5 V	[1]	-	60	A
I_{DM}	peak drain current	pulsed; t_p ≤ 10 µs; Fig. 2	[1]	-	230	A
T_{stg}	storage temperature			-40	150	°C
T_j	junction temperature			-40	150	°C
$T_{sld(M)}$	peak soldering temperature			-	260	°C

[1] Limited by package



$$P_{der} = \frac{P_{tot}}{P_{tot(25°C)}} \times 100\,\%$$

Fig. 1. Normalized total power dissipation as a function of mounting base temperature



T_{mb} = 25 °C; I_{DM} is a single pulse

Fig. 2. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

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9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	Fig. 3		-	-	0.3	K/W
$R_{th(j-mb)}$	thermal resistance from junction to mounting base			-	-	1.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		[1]	-	-	33	K/W

[1] $R_{th(j-a)}$ is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board.

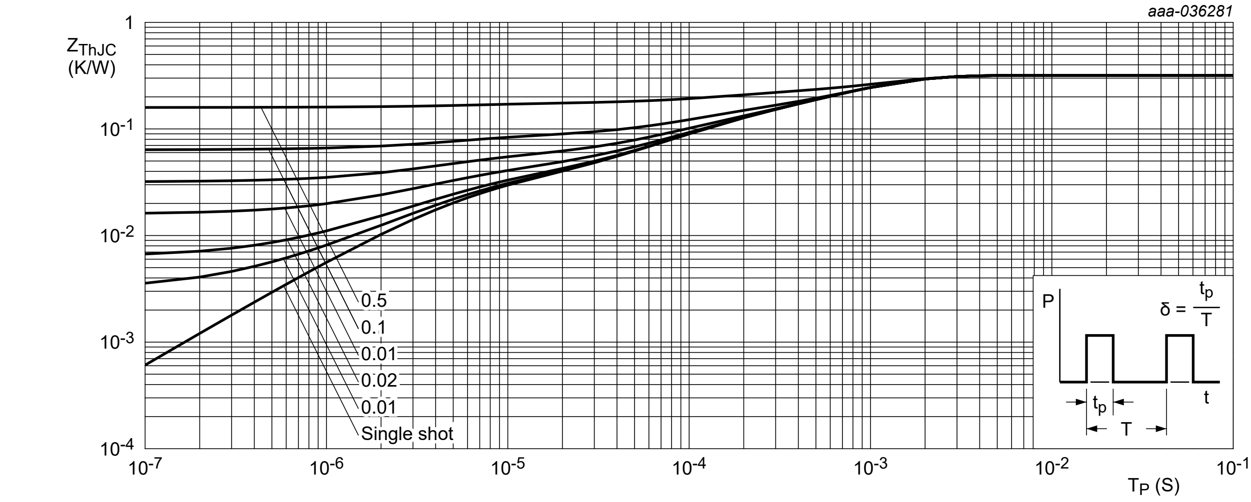

Fig. 3. Transient thermal impedance from junction to case as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 400 µA; V_{GS} = 0 V; T_j = 25 °C		100	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 9 mA; V_{DS} = V_{GS}; T_j = 25 °C; Fig. 8		0.8	1.1	2.5	V
I_{DSS}	drain leakage current	V_{DS} = 80 V; V_{GS} = 0 V; T_j = 25 °C		-	80	350	µA
I_{GSS}	gate leakage current	V_{GS} = 5 V; V_{DS} = 0 V; T_j = 25 °C		-	20	5000	µA
		V_{GS} = 5 V; V_{DS} = 0 V; T_j = 125 °C		-	600	9000	µA
		V_{GS} = -4 V; V_{DS} = 0 V; T_j = 25 °C		-	60	400	µA
R_{DSon}	drain-source on-state resistance	V_{GS} = 5 V; I_D = 25 A; T_j = 25 °C; Fig. 9; Fig. 10; Fig. 11; Fig. 12		-	2.4	3.2	mΩ
R_G	gate resistance	f = 5 MHz; T_j = 25 °C		-	2.2	-	Ω

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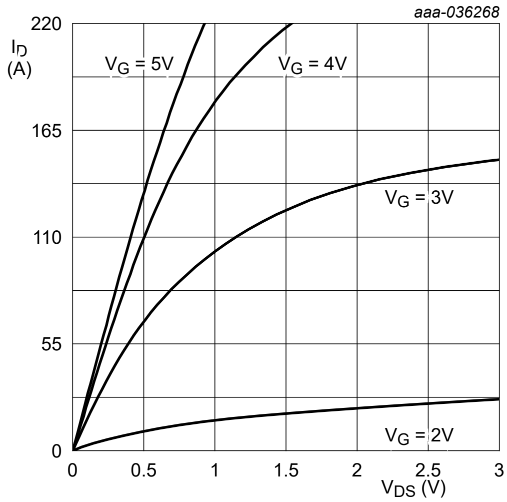
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	I_D = 25 A; V_{DS} = 50 V; V_{GS} = 5 V; T_j = 25 °C; Fig. 13; Fig. 14		-	9.2	12	nC
Q_{GS}	gate-source charge			-	1.9	-	nC
Q_{GD}	gate-drain charge			-	1.7	-	nC
C_{iss}	input capacitance	V_{DS} = 50 V; V_{GS} = 0 V; f = 100 kHz; T_j = 25 °C; Fig. 15		-	1000	-	pF
C_{oss}	output capacitance			-	460	-	pF
C_{rss}	reverse transfer capacitance			-	8.2	-	pF
$C_{o(er)}$	effective output capacitance, energy related	0 V ≤ V_{DS} ≤ 50 V; V_{GS} = 0 V; T_j = 25 °C; Fig. 16	[1]	-	700	-	pF
$C_{o(tr)}$	effective output capacitance, time related	0 V ≤ V_{DS} ≤ 50 V; V_{GS} = 0 V; T_j = 25 °C	[2]	-	1020	-	pF
Q_{oss}	output charge	V_{GS} = 0 V; V_{DS} = 50 V; T_j = 25 °C	[3]	-	50	-	nC
Source-drain characteristics							
V_{SD}	source-drain voltage	I_S = 0.5 A; V_{GS} = 0 V; T_j = 25 °C; Fig. 17; Fig. 18; Fig. 19; Fig. 20		-	1.5	-	V

[1] $C_{O(er)}$ is the fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 50 V

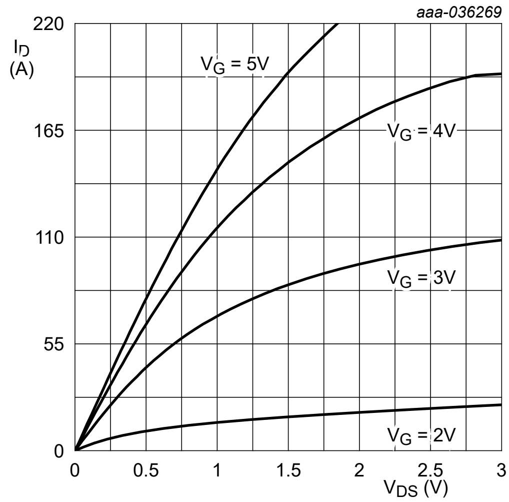
[2] $C_{O(tr)}$ is the fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 50 V

[3] Q_r is not specified separately from Q_{oss} for e-mode GaN FETs, since $Q_r = Q_{oss} + Q_D$, and Q_D = 0. (Q_D is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q_{oss} have to be transferred for e-mode GaN FETs.)



T_j = 25 °C

Fig. 4. Output characteristics: drain current as a function of drain-source voltage; typical values



T_j = 125 °C

Fig. 5. Output characteristics: drain current as a function of drain-source voltage; typical values

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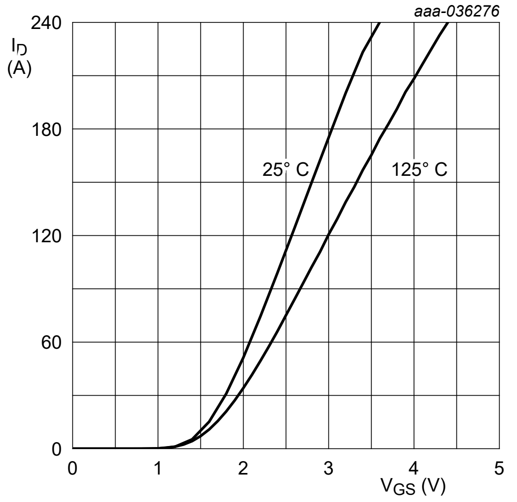
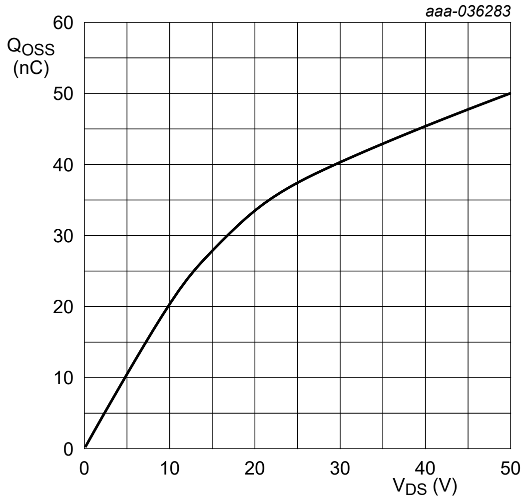
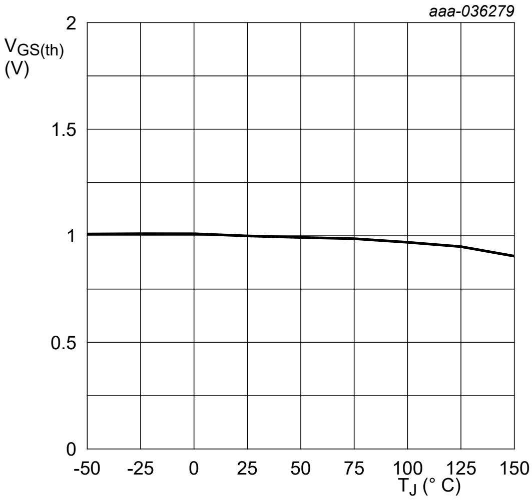


Fig. 6. Transfer characteristics; drain current as a function of gate-source voltage; typical values



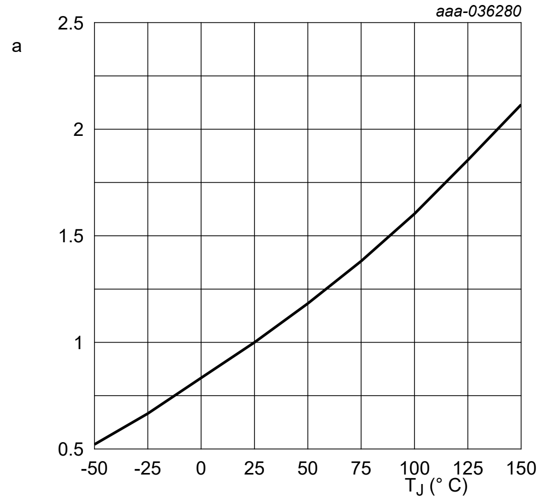
Freq. = 100 kHz

Fig. 7. Output charge as a function of drain-source voltage; typical values



I_D = 9 mA ; V_{DS} = V_{GS}

Fig. 8. Gate-source threshold voltage as a function of junction temperature



$$a = \frac{R_{DSon}}{R_{DSon\,(25°C)}}$$

Fig. 9. Normalized drain-source on-state resistance factor as a function of junction temperature

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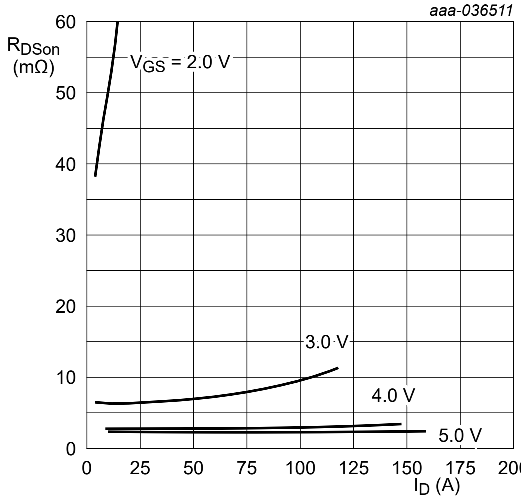

Fig. 10. Drain-source on-state resistance as a function of drain current ; typical values

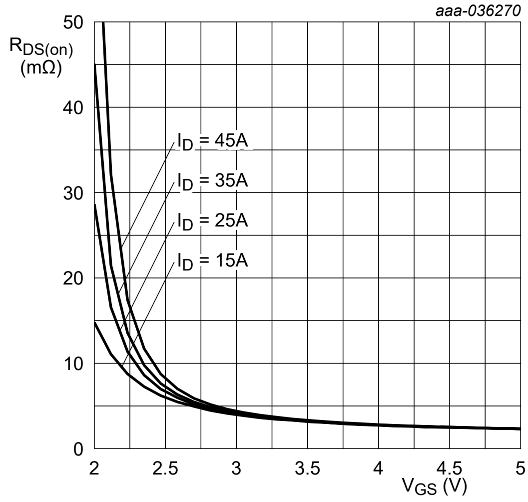

Fig. 11. Drain-source on-state resistance as a function of gate-source voltage; typical values

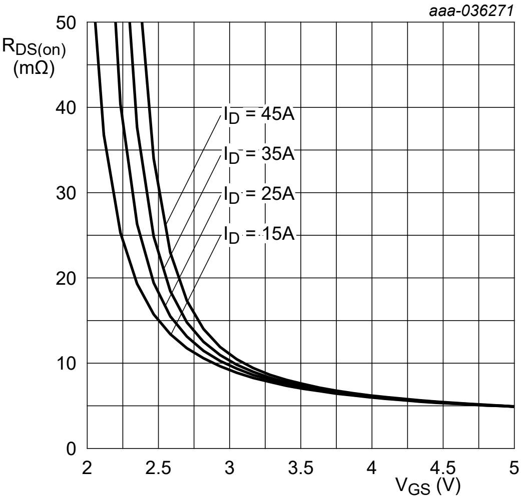

Fig. 12. Drain-source on-state resistance as a function of gate-source voltage; typical values

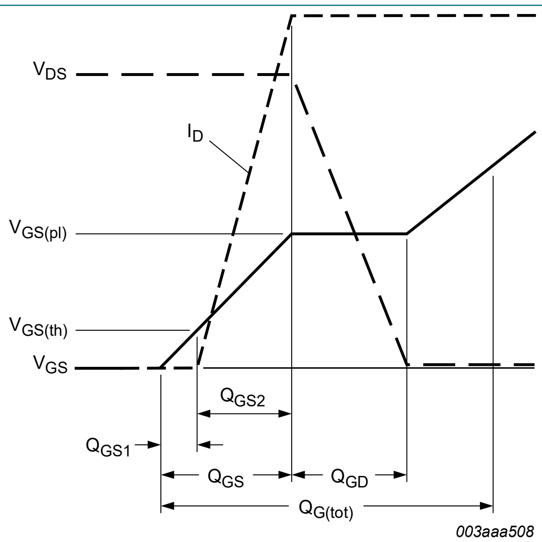

Fig. 13. Gate charge waveform definitions

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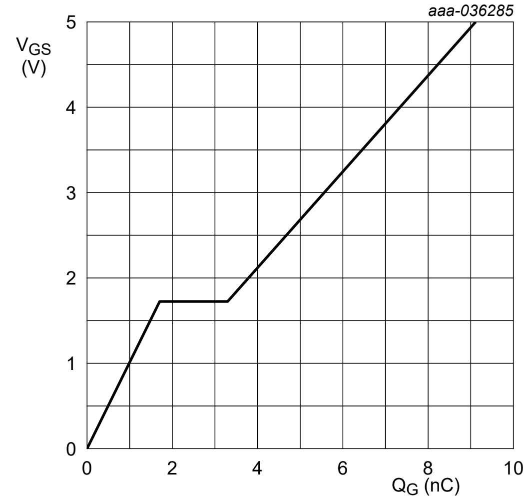


T_J = 25 ° C ; I_D = 25 A

Fig. 14. Gate-source voltage as a function of gate charge; typical values

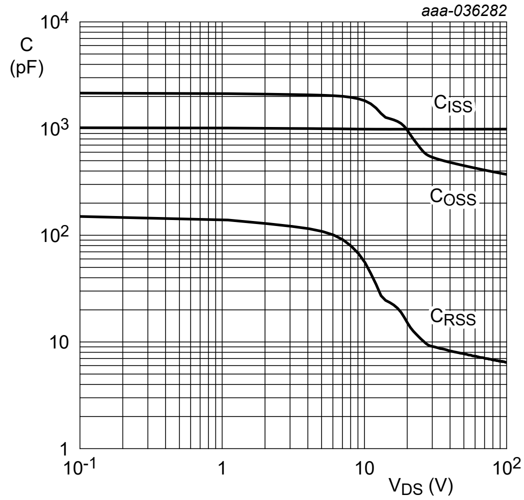
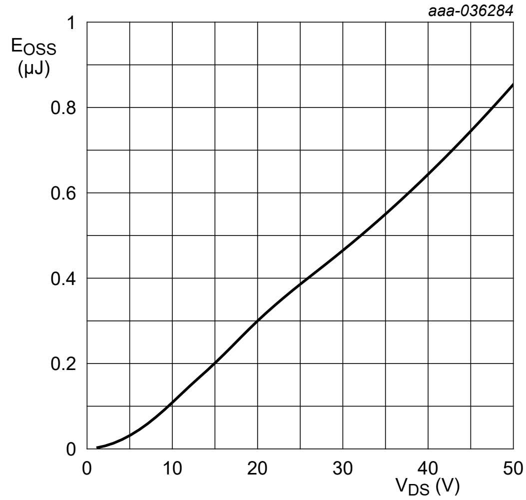
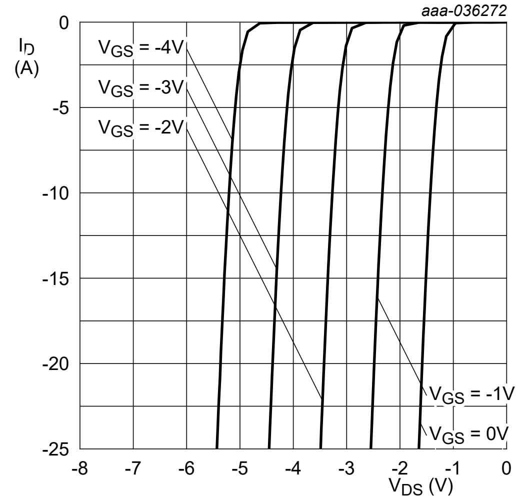


Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



Freq. = 100 kHz

Fig. 16. COSS stored energy as a function of drain-source voltage; typical values



T_j = 25 °C

Fig. 17. Source current as a function of source-drain voltage; typical values

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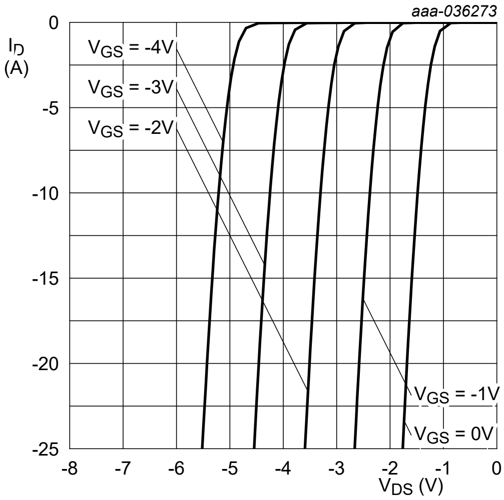
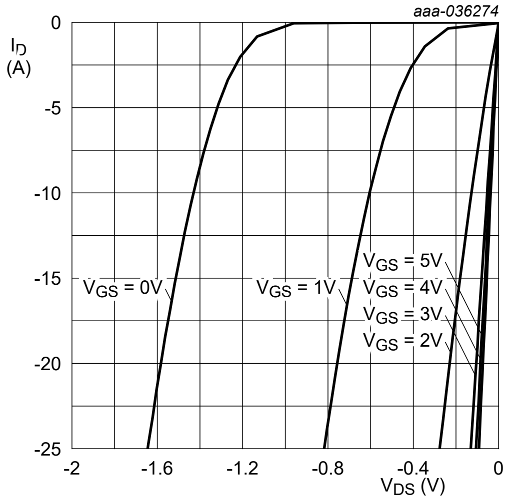


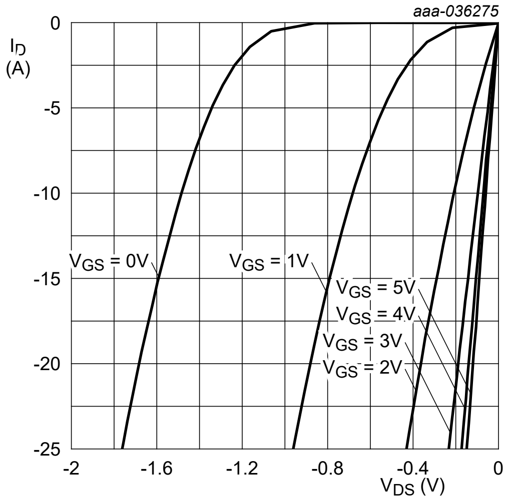
T_j = 125 °C

Fig. 18. Source current as a function of source-drain voltage; typical values



T_j = 25 °C

Fig. 19. Source current as a function of source-drain voltage; typical values



T_j = 125 °C

Fig. 20. Source current as a function of source-drain voltage; typical values

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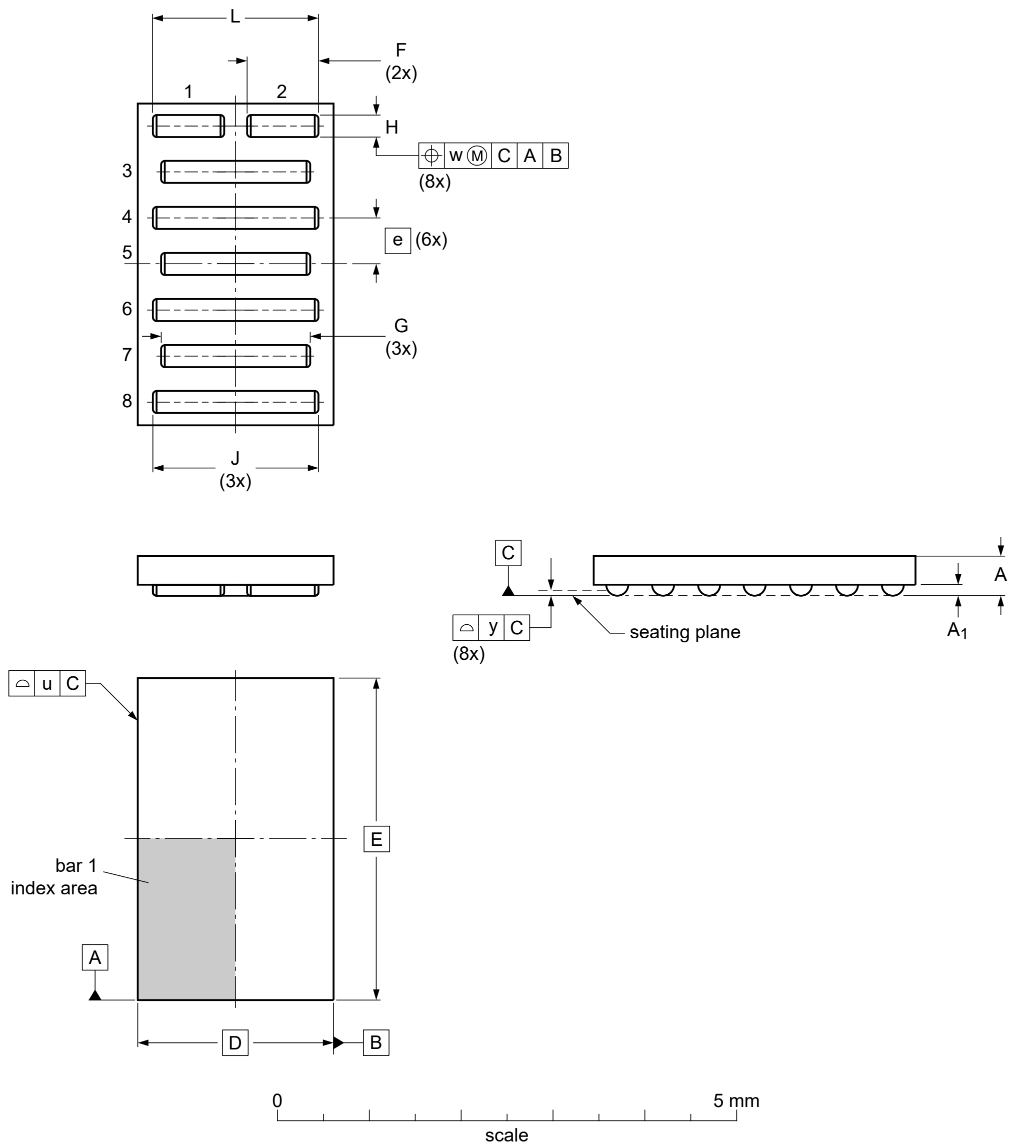
11. Package outline

WLCSP8: wafer level chip-scale package; 8 solder bars; body: 3.5 x 2.13 x 0.429 mm **WLCSP8-SOT8072**



Dimensions (mm are the original dimensions)

Unit		A	A_1	D	E	e	F	G	H	J	L	y	u	w
mm	max	0.464	0.14	2.13 BSC	3.5 BSC	0.5 BSC	0.795	1.645	0.27	1.82	1.82	0.05	0.025	0.1
	nom	0.429	0.12				0.775	1.625	0.25	1.8	1.8			
	min	0.394	0.1				0.755	1.605	0.23	1.78	1.78			

wlcsp8-sot8072_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
WLCSP8-SOT8072		MO-211 compatible				23-03-03

Fig. 21. Package outline WLCSP8 (WLCSP8-SOT8072)

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12. Soldering

Footprint information for reflow soldering of WLCSP8-SOT8072 package **WLCSP8-SOT8072**

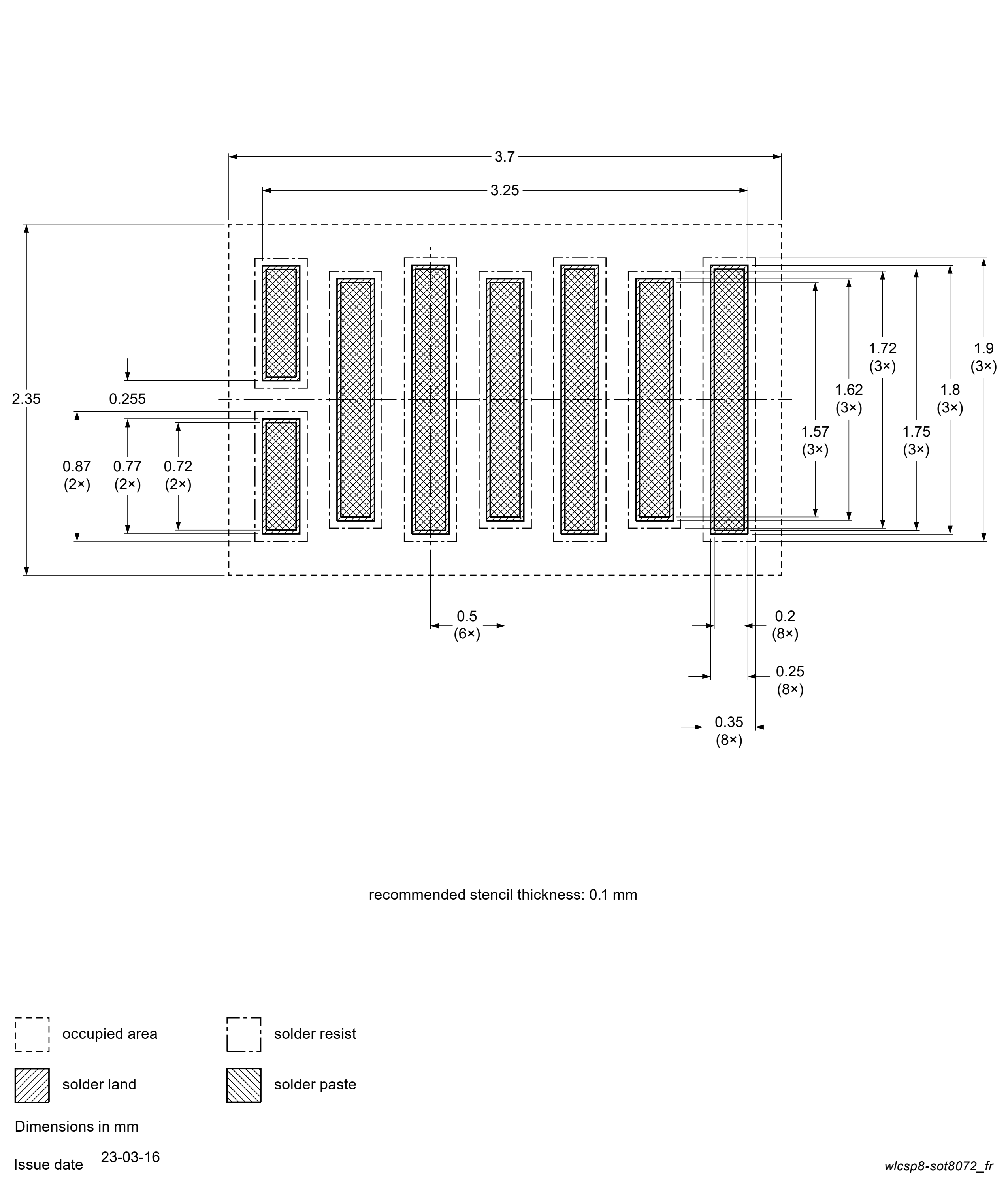

Fig. 22. Reflow soldering footprint for WLCSP8 (WLCSP8-SOT8072)

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13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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